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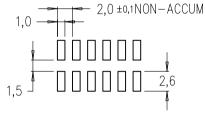
		1 2									
PRODUCT NO	POS	DIM X	DIM Y								
94262-X04	2X2	2	4								
X06	2X3	4	6								
X08	2X4	6	8								
X10	2X5	8	10								
X12	2X6	10	12								
X14	2X7	12	14								
X16	2X8	14	16								
X18	2X9	16	18								
X20	2X10	18	20								
X22	2X11	20	22								
X24	2X12	22	24								
X26	2X13	24	26								
X28	2X14	26	28								
X30	2X15	28	30								
X32	2X16	30	32								
X34	2X17	32	34								
X36	2X18	34	36								
X38	2X19	36	38								
X40	2X20	38	40								
X42	2X21	40	42								
X44	2X22	42	44								
X46	2X23	44	46								
X48	2X24	46	48								
X50	2X25	48	50								

(6) SOLDER TAIL PLATING:

- a) SOLDERTAIL OF P/N:94262-XXX IS PLATED WITH 3.81um MIN TIN/LEAD (90/10) PLATING OVER 1.27um MIN NI UNDERPLATE.
- b) SOLDERTAIL OF P/N: 94262-XXXLF IS PLATED WITH 3.81um MIN 100% MATTE TIN PLATING OVER 1.27um MIN NI UNDERPLATE.
- 7 PACKAGING:
 - (a) STANDARD PACKAGING IN PLASTIC BAG.
 - (b) SPECIFY 94262-XXXT FOR TUBE PACKAGING.
 - (c) SPECIFY 94262-XXXTR FOR TAPE AND REEL PACKAGING. A PICK-UP CAP IS PROVIDED IN THE CENTRE OF THE PRODUCT (SEE FIG.1) FOR PICK AND PLACE APPLICATION.
- COPLANARITY OF SOLDER LEADS TO BE WITHIN 0,10mm.
- 9 PRODUCT DESCRIPTION CODE:

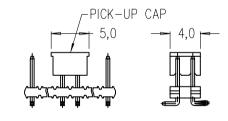
XXXXX-XXXLF LEAD FREE (6)(12) EXTENSION NUMBER BASE NUMBER

- 10 THE HOUSING WILL WITHSTAND EXPOSURE TO 255° C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
- 11 THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.57MM MINIMUM THICK CIRCUIT BOARD.
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008



RECOMMENDED PAD LAYOUT

ACAD



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FIG. 1 NOTE 7 (c)

NOTES

1 MATERIAL

BODY: HIGH TEMPERATURE PLASTIC UL 94V-O BLACK

PIN : COPPER ALLOY

- 2 TOLERANCE UNLESS OTHERWISE NOTED ±0,25
- DIM 1.0 APPLIES TO MOLDED SIDE(S) ONLY. IF SIDE(S) ARE BROKEN, DIM 1.5 MAX APPLIES.
- RECESS APPLIES TO MOLDED SIDE(S) ONLY.
- 5 PLATING ON MATING LENGTH:
- -3XX --- 0.38um Au OVER 1.27um MIN NICKEL UNDERPLATE.
- -5XX --- 0.38um PdNi W Au FLASH OVER 1.27um MIN NICKEL UNDERPLATE.
- -6XX --- 0.76um PdNi W Au FLASH OVER 1.27um MIN NICKEL UNDERPLATE.

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PDM: Rev:C

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